

描述 / Descriptions

表面贴装整流二极管，反向电压：50V~1000V，正向电流：3.0A， SMC 封装。
Surface Mount General Purpose Silicon Rectifiers, Reverse Voltage : 50 to1000V,Forward Current:3.0A ,SMC thin package.

特征 / Features

玻璃钝化芯片，无铅符合欧盟 RoHS 指令 2011/65/EU，适用表面贴装。无卤产品。
Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. Halogen free product.

用途 / Applications

一般用途。
General purpose.

内部等效电路 / Equivalent Circuit

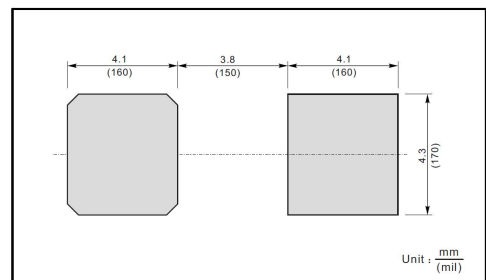


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。 See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		S3AC	S3BC	S3DC	S3GC	S3JC	S3KC	S3MC	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	90							A
Typical Junction Capacitance at VR=4V f=1MHz	C_j	40							pF
Typical Thermal Resistance ¹⁾	$R_{\theta JA}$	40							°C/W
	$R_{\theta JC}$	16							
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150							°C

Note:

1) P.C.B. mounted with 2.0 X 2.0" (5 X5 cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating							单位 Unit
			S3AC	S3BC	S3DC	S3GC	S3JC	S3KC	S3MC	
Maximum Instantaneous Forward Voltage	V_F	$I_F=3.0A$	1.0							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25^\circ C$	5.0							μA
		$T_a=125^\circ C$	100							μA

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

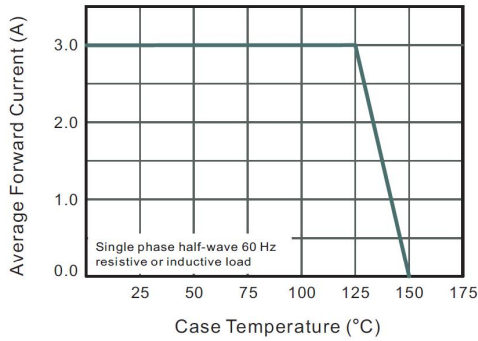


Fig.2 Typical Reverse Characteristics

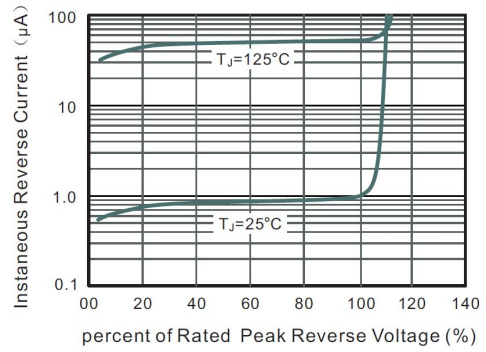


Fig.3 Typical Forward Characteristic

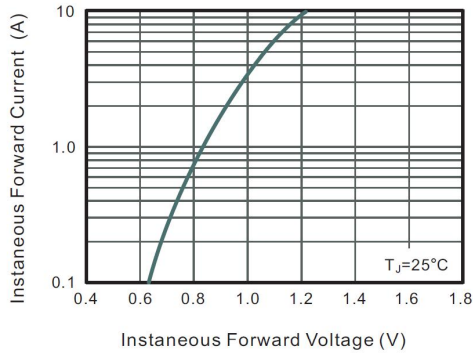


Fig.4 Typical Junction Capacitance

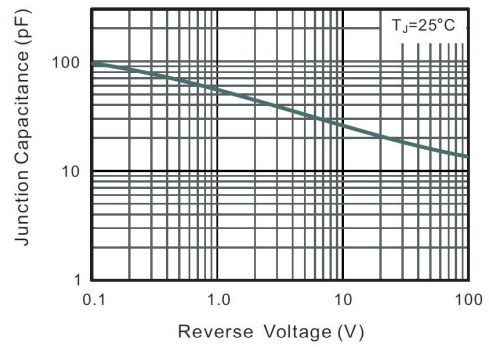
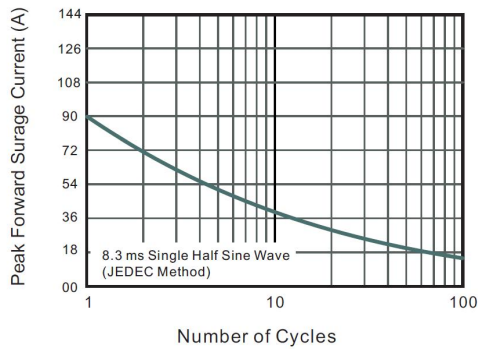
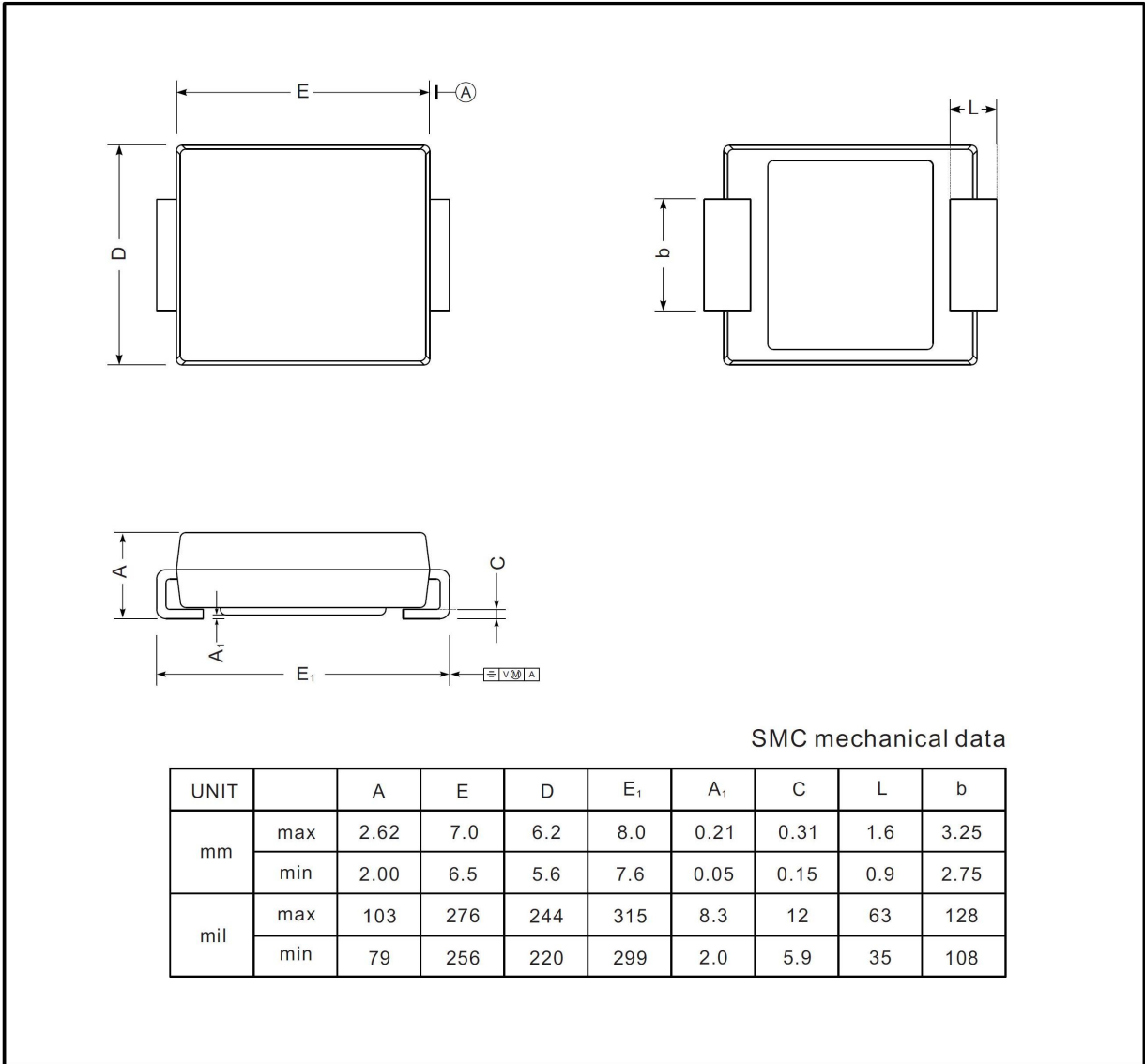


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



外形尺寸图 / Package Dimensions

SMC



Marking

Type number	Marking code
S3AC	S3A
S3BC	S3B
S3DC	S3D
S3GC	S3G
S3JC	S3J
S3KC	S3K
S3MC	S3M

印章说明 / Marking Instructions



说明：

S3A： 为型号代码

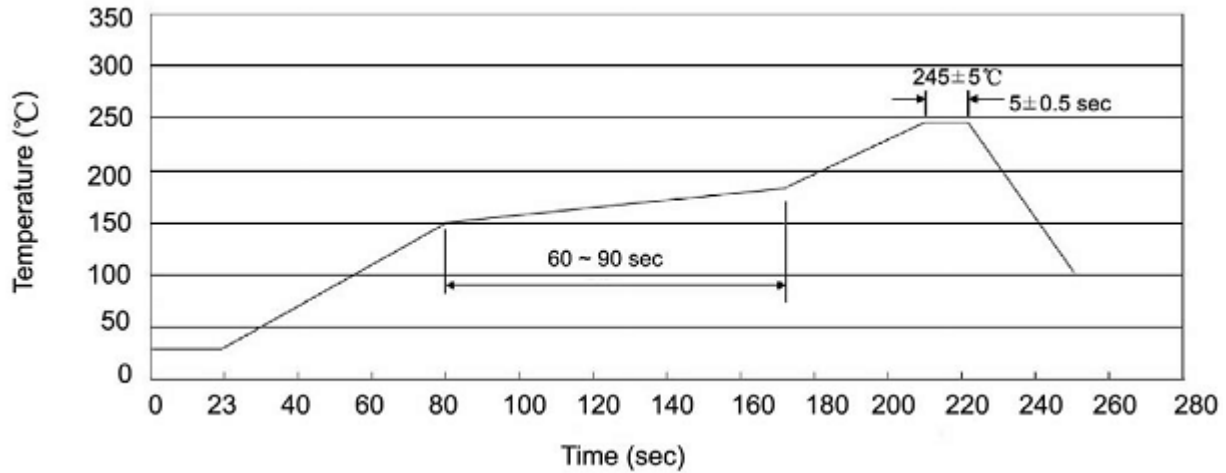
****： 为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

S3A： Product Type Code

****： Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMC	3000	2	6000	6	36000	13" ×16	337X337X49	380X335X366

使用说明 / Notices